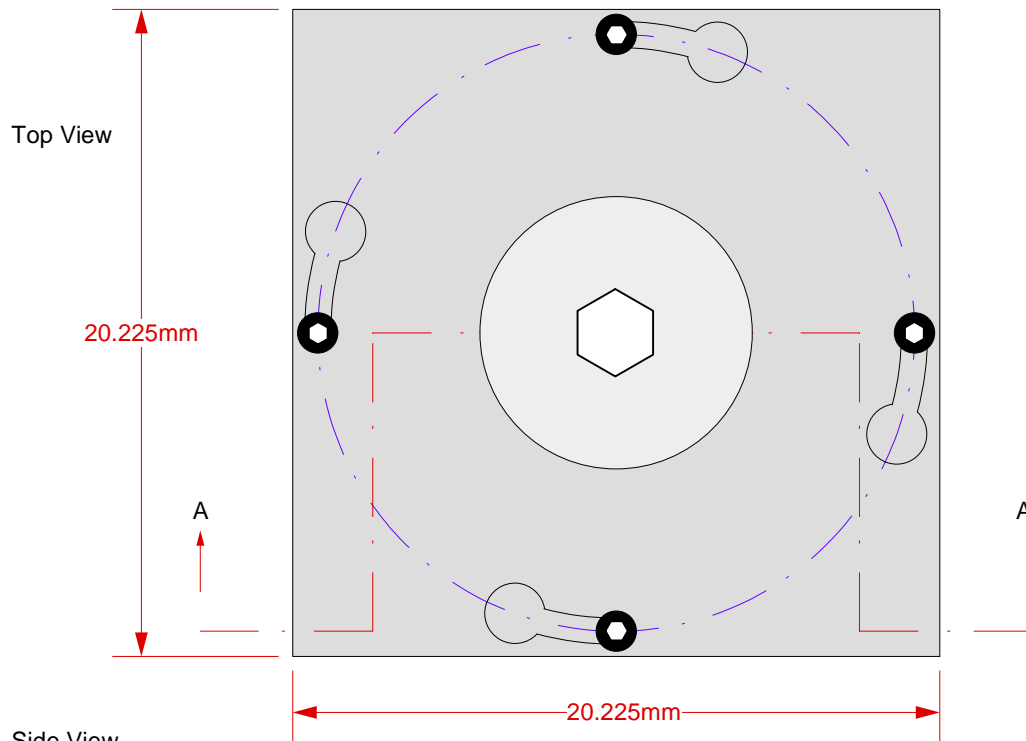
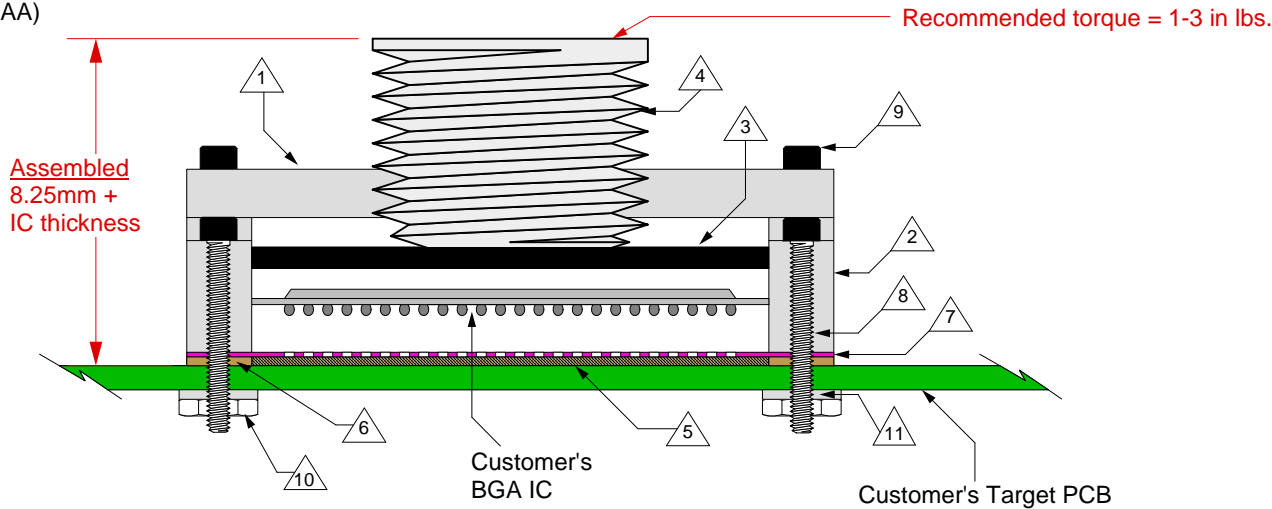


GHz BGA Socket - Direct mount, solderless



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Black anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.75mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-BGA-6050 Drawing

Status: Released

Scale: -

Rev: C



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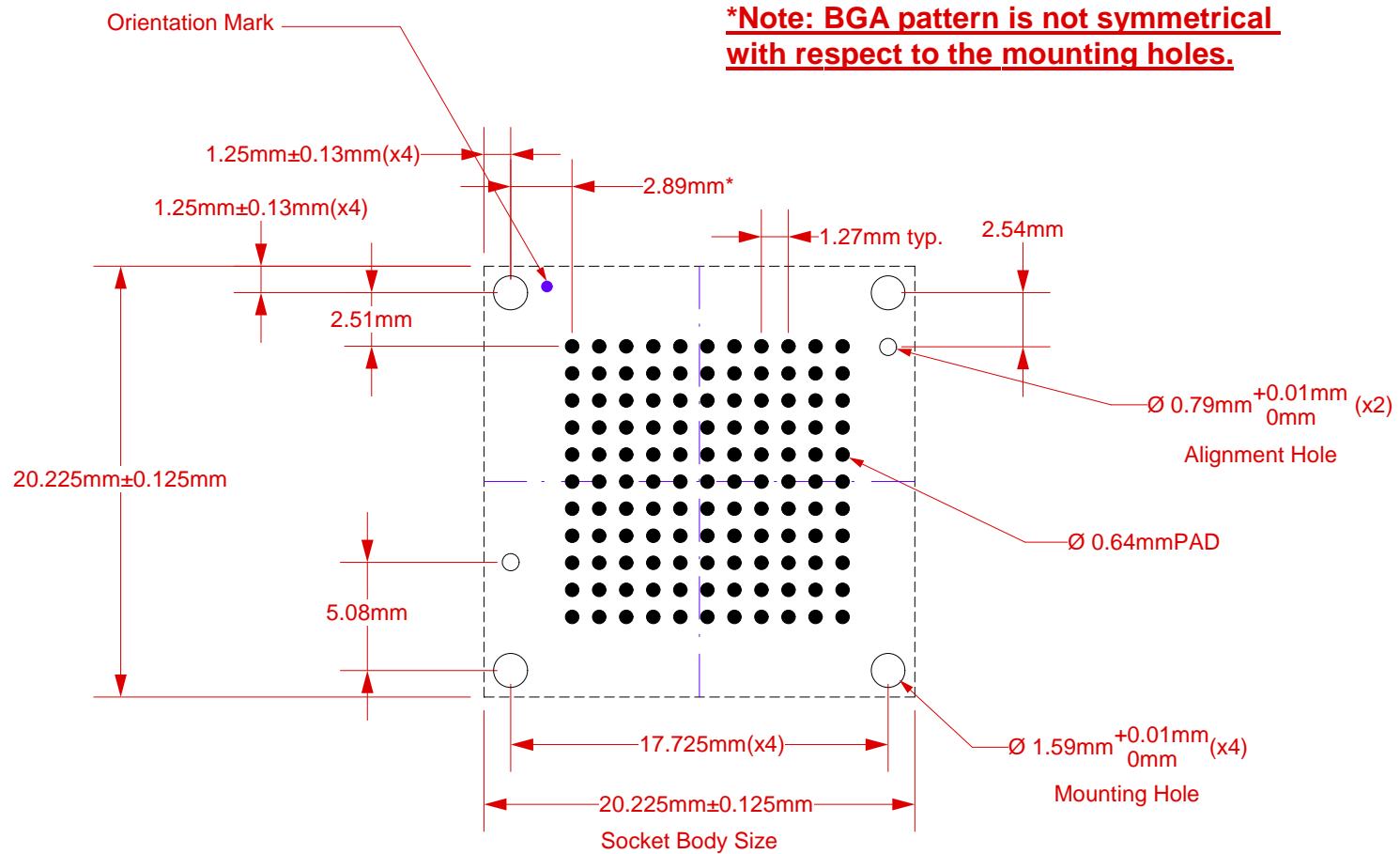
Drawing: H. Hansen

Date: 5/17/02

File: SG-BGA-6050 Dwg.mcd

Modified: 7/2/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.



Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

Target PCB Recommendations


Total thickness: 1.6mm min.

Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

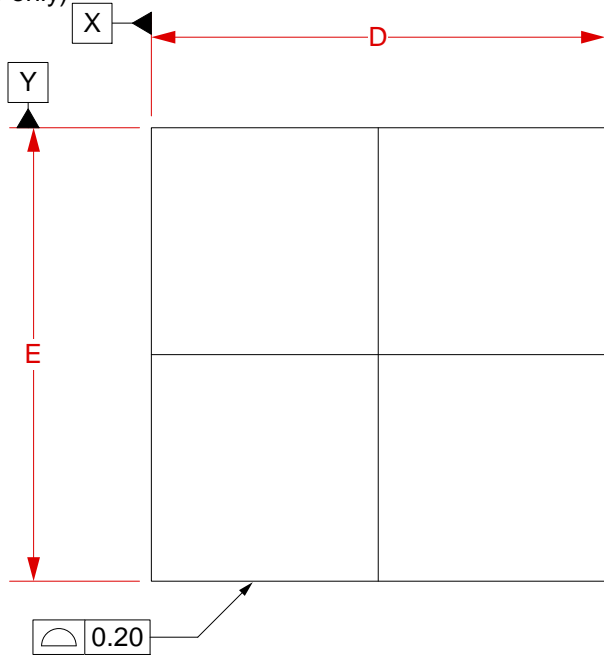
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

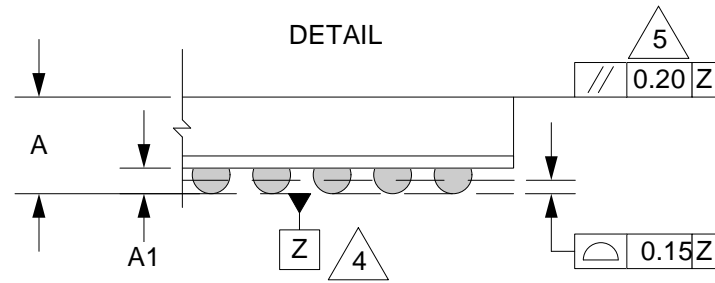
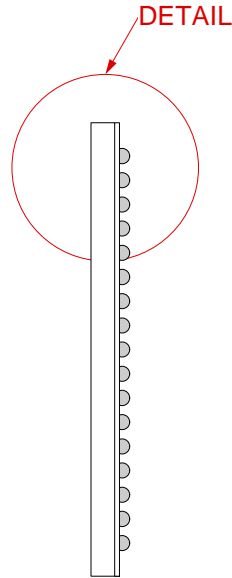
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	<p>Drawing: H. Hansen</p>	<p>Date: 5/17/02</p>		
	<p>File: SG-BGA-6050 Dwg.mcd</p>	<p>Modified: 7/2/09, AE</p>		

Top View
(reference only)

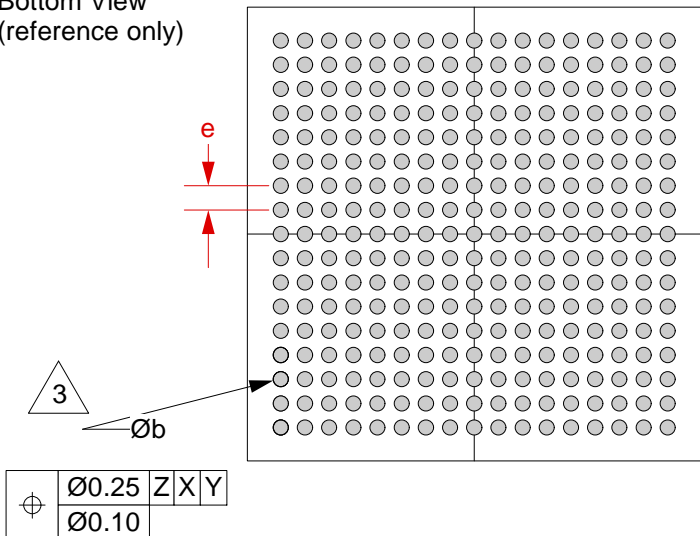
Compatible BGA Spec



Side View
(reference only)




Bottom View
(reference only)



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.3
A1	0.5	0.7
b		0.9
D	15.00 BSC	
E	15.00 BSC	
e	1.27 BSC	

Array 11x11

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	Drawing: H. Hansen	Date: 5/17/02		
	File: SG-BGA-6050 Dwg.mcd	Modified: 7/2/09, AE		